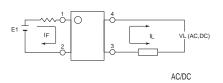
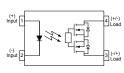


Parameter	Symbol	Rating	Units	
Load Voltage	VL	40	V	
Load Current	l∟	2	Α	
On-Resistance	Ron	0.06	Ω	
On-Resistance	V/IO	5000	Vrms	





- LED Anode
- 2. LED Cathode
- 3.4. Drain(MOS FET)



#### SMD-4

# DIP-4

### **APSEMI PhotoRelays**

APSEMI Photorelays are the most reliable, technically advanced logic-to-power interface devices. Their basic function is to take a low current signal from a microprocessor to control the switching of both AC and DC loads, while providing an isolation barrier between logic and power. While this function is common to all relays, Photorelays provide distinct advantages over their mechanical counterparts including:

- Long life (No limit on mechanical and electrical
- lifetime)Bounce-free switching
- Higher speed and high frequency switching
- Higher sensitivity (less power consumption)
- Immunity to EMI or RFI

- No have voltaic arc, bounce, and noise More
- resistant to vibration and impact AC or DC load
- switching
- Small package size

### **Function**

APSEMI PhotoRelays operate by taking a low level input current (<5mA) that energizes an input Infrared LED, which is optically-coupled to a Photo-diode array chip. This IC in turn generates a photo voltage that powers two MOSFETs typically connected in a source-to-source con¦ guration, allowing for both AC and DC output loads. Photorelay basically move photons to accomplish their switching function, they incur no mechanical wear and tear, providing consistent reliable switching.

# Applications

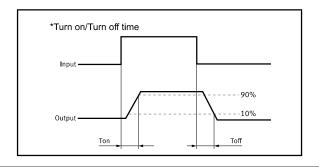
These advantages make APSEI Photorelays the ideal choice for:

- Telecom/Datacom switching
- Multiplexers
- Meter reading systems
- Data acquisition
- Medical equipment
- Battery monitoring
- I/O Sub-Systems

- Robotics
- Aerospace
- Home/Safety security systems
- Process Control
- Energy Management
- Reed Relay EMR Replacement
- Programmable Controllers

#### **TPYES**

Category	Cotogony	Output Rating		Package	Part No.	Packing Quantity			
	Load Voltage	Load Current	Fait No.						
	AC/DC	401/	DIP-4	APY211E	50pcs /tube				
AC/DC	40V	2A	SMD-4	APY211EH	1000pcs /reel				





# Absolute Maximum Ratings (Ta = 25°C)

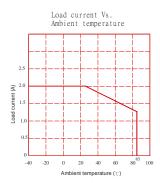
Item		Symbol	Value	Units	Note	
	Continuous LED Current	ĪF	50	mA		
Input	Peak LED Current	Ігр	1000	mA	f=100Hz, duty=1%	
·	LED Reverse Voltage	VR	5	V		
	Input Power Dissipation	Pin	75	mW		
	Load Voltage	VL	40	V(AC peak or DC)		
	Load Current	l.	2.0	А		
Output	Peak Load Current	Peak	4.0	А	100ms(1 pulse)	
	Output Power Dissipation	Pout	1.8	W		
Total Power	r Dissipation	Рт	2	W		
I/O Breakdo	own Voltage	V <sub>I/O</sub>	5000	Vrms	RH=60%, 1min	
Operating Temperature		Торг	-40 to 85	°C		
Storage Temperature		T <sub>stg</sub>	-40 to 100	°C		
Pin Soldering Temperature		Tsol	260	°C	10 sec max.	

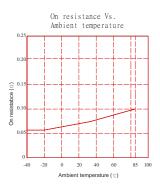
# Electrical Characteristics (Ta = 25°C)

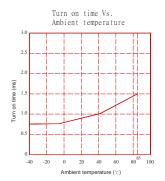
Item		Symbol	MIN.	TYP.	MAX.	Units	Conditions	
	LED Forward Voltage	VF		1.2	1.4	٧	I⊧=10mA	
	Operation LED Current	Fon		0.5	3.0	mA		
Input	Recovery LED Current	Foff		0.35	0.5	mA		
	Recovery LED Voltage	V <sub>Foff</sub>	0.7			٧		
							I⊧=5mA,I∟=100mA,	
	On-Resistance	Ron		0.06	0.1	Ω	Time to flow is within 1 sec.	
Output								
	Off-State Leakage	Leak				1 uA	V∟=Rating	
	Current	ILeak			1		VL-INating	
	Output Capacitance	Cout		190		pF	V∟=0, f=1MHz	
Transmis	Turn-On Time	Ton		0.8	1.5	ms	I⊧=5mA, I∟=100mA,	
sion	Turn-Off Time	Toff		0.02	0.5	ms		
Counted	I/O Isolation Resistance	R <sub>I/O</sub>	10 <sup>10</sup>			Ω	DC500V	
Coupled	I/O Capacitance	Cı/o		0.8	1.5	pF	f=1MHz	

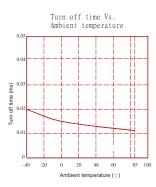


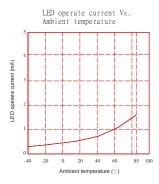
# **Engineering Data**

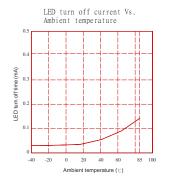


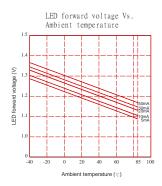


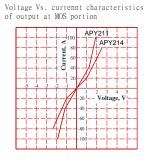


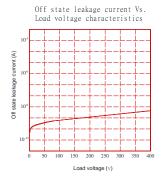


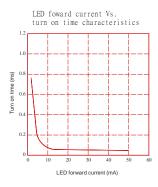


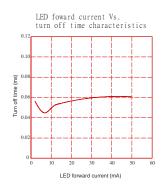


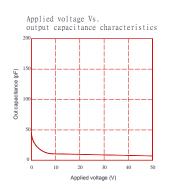








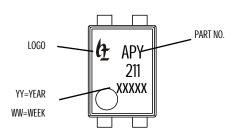




# **Dimensions and DIP-4 Package**

Unit: mm

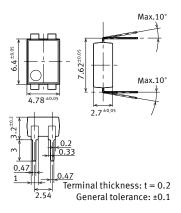
# Marking



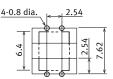
Lable



#### Surface mount terminal type



PC board pattern (BOTTOM VIEW)



Tolerance: ±0.1

**DIP Tape dimensions** 

Unit: mm inch Tolerance: +0.2 +.007

Devices are packaged in a tube so that pin No. 1 is on the stopper B side. Observe correct orientation when mounting them on PC boards.

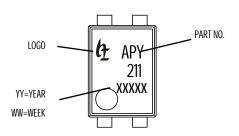


Page 4



# Dimensions and SMD-4 Package Unit: mm

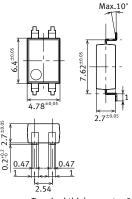
# Marking



### Lable

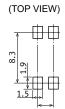


#### Surface mount terminal type



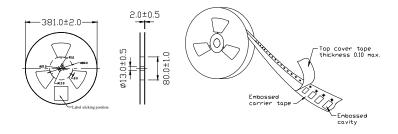
Terminal thickness: t = 0.2 General tolerance: ±0.1

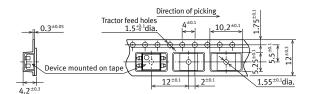
# Recommended mounting pad



Tolerance: ±0.1

### Tape dimensions (tape reel)

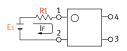


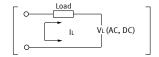




# **Using Methods**

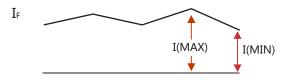
Examples of resistance value to control LED forward current (IF=5mA)





E1	R1 (Approx)
3.3V	300 Ω
5.0V	600 Ω
12V	1.9KΩ
24V	4.1K Ω

LED forward current must be more than 5mA, at I(MIN), and less than 30mA, at I(MAX).



### **Recommended Operating Conditions**

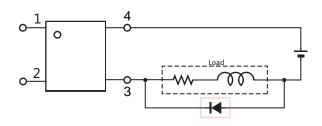
Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value):

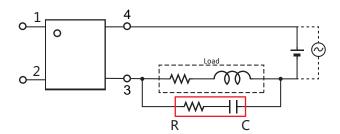
Characteristic	Symbol	Min	Тур.	Max	Unit
Forward current	l <sub>F</sub>	5.0	7.0	30	mA

#### **Protection Circuit**

Clamp diode is connected in parallel with the load. Absorb capacity with external diode.

CR Snubber is connected in parallel with the load. Absorb capacity with buffer capacity.





When adding diodes, buffer circuits (C-R), and other protections, they need to be installed near the MOS RELAY to be effective. Adding protection elements may result in a slow reset time, so adjust them according to the actual situation before use.

Note: When developing designs using this product, perform the expected performance of the equipment under the operating conditions recommended by the guidelines in this document. Continuous use under heavy loads (including, but not limited to, the application of high temperatures/current/voltage and significant changes in temperature, etc.) may result in deterioration of the reliability of this product.



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